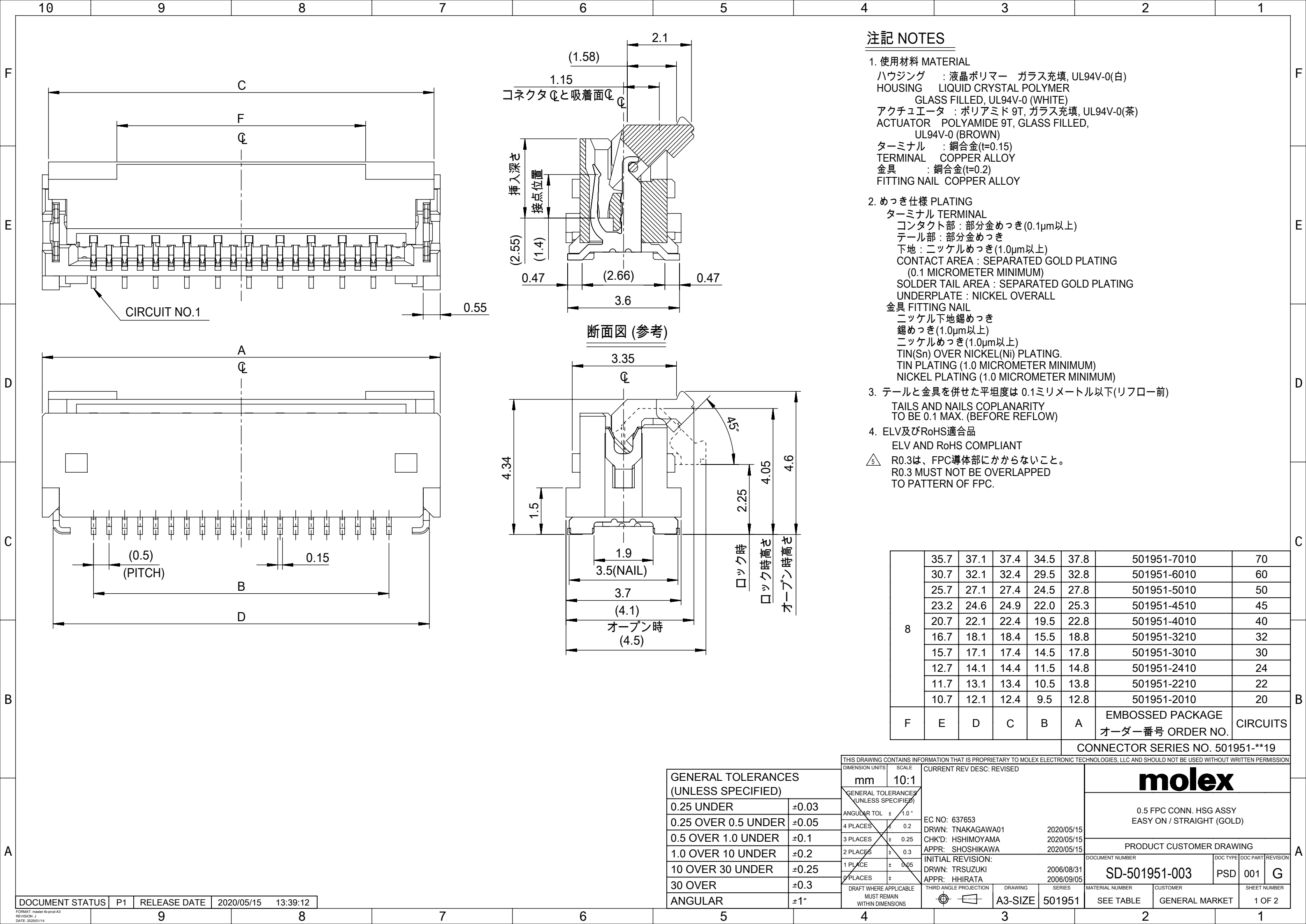
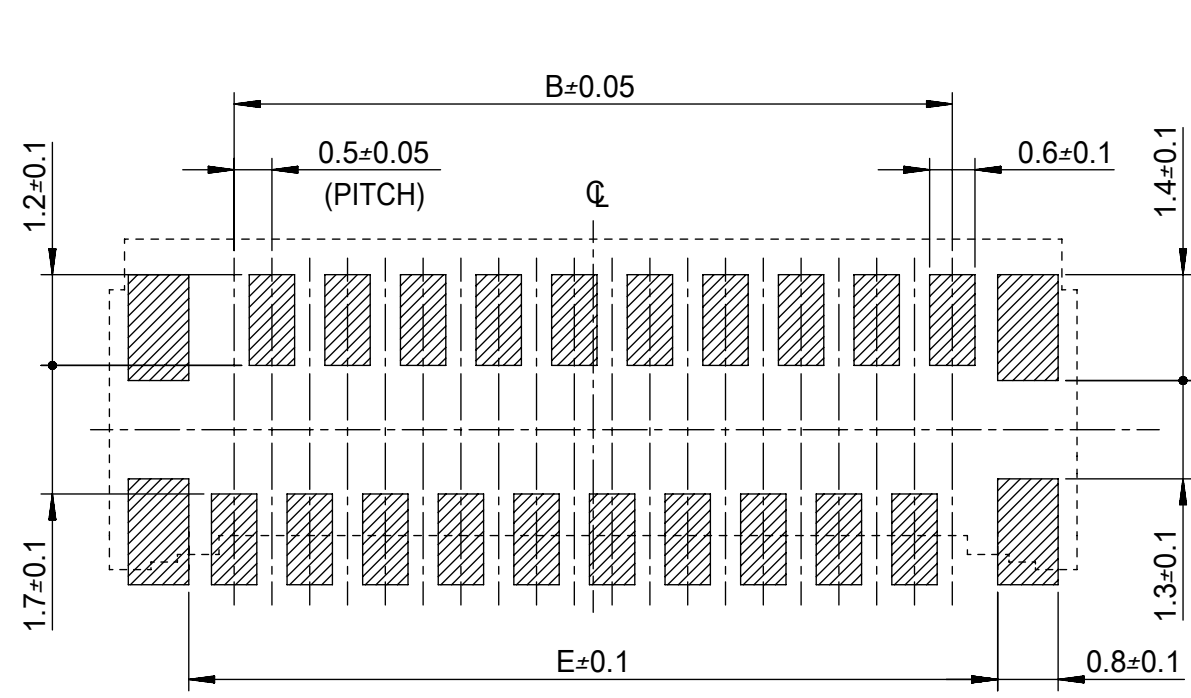






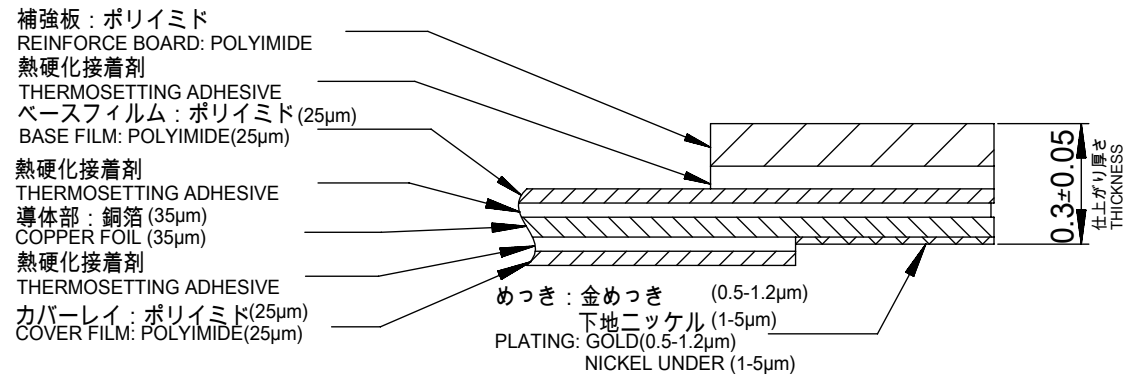
参考基板レイアウト (マウント面)

P.C.BOARD PATTERN DIMENSION(REF.)
(MOUNT AREA)

FPCについて ABOUT FPC

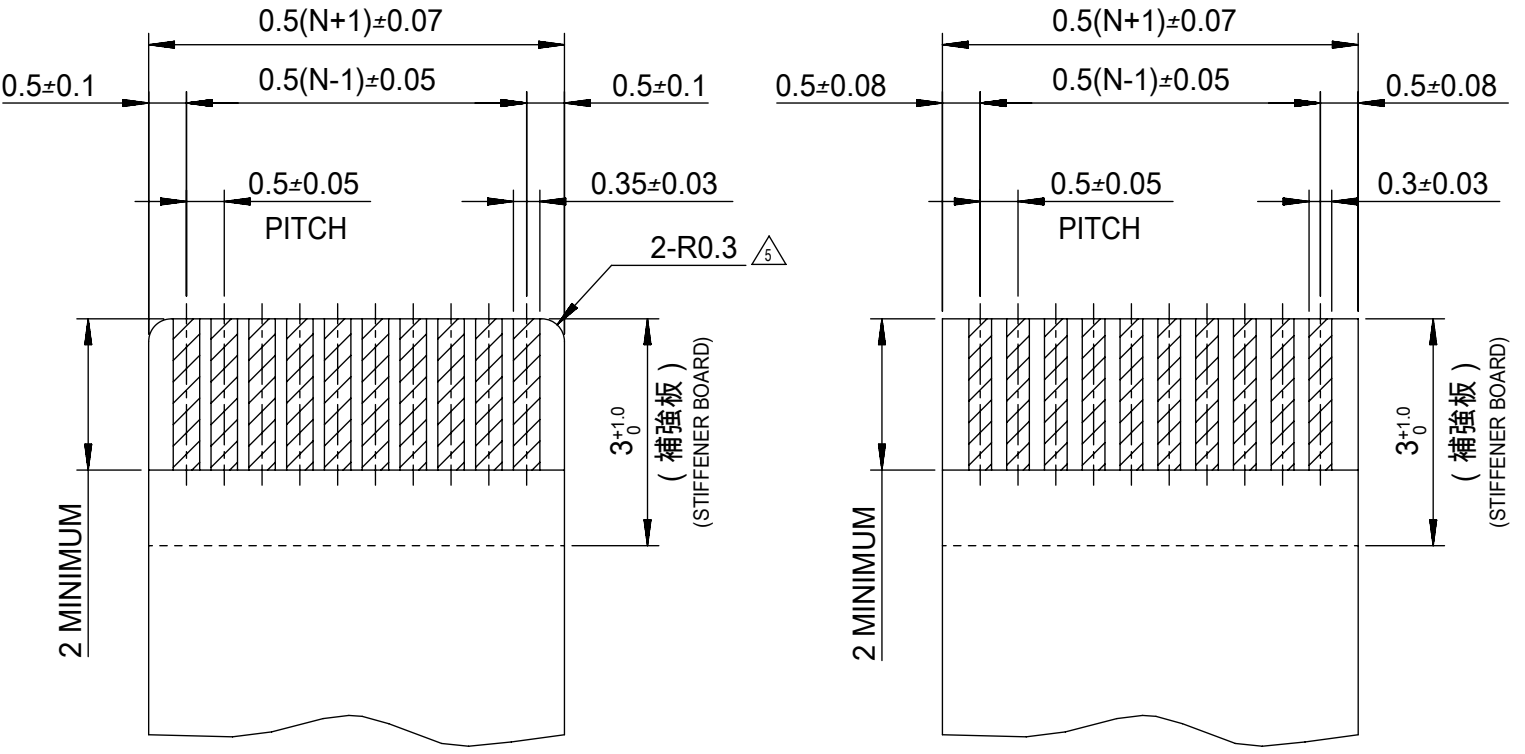
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。

RECOMMENDED MATERIAL/THICKNESS.
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.
THERE IS A POSSIBILITY THAT THE PRESCRIPT TEMPERATURE OF FFC IS SET TO SINGLE IT.



FPC構成推奨仕様

STRUCTURE OF FPC



適合FPC推奨寸法

N: 極数
N:CIRCUITS

APPLICABLE FPC
RECOMMENDED DIMENSION

(仕上がり厚さ : 0.3±0.05)
(THICKNESS : 0.3±0.05)

適合FFC推奨寸法

N: 極数
N:CIRCUITS

APPLICABLE FFC
RECOMMENDED DIMENSION

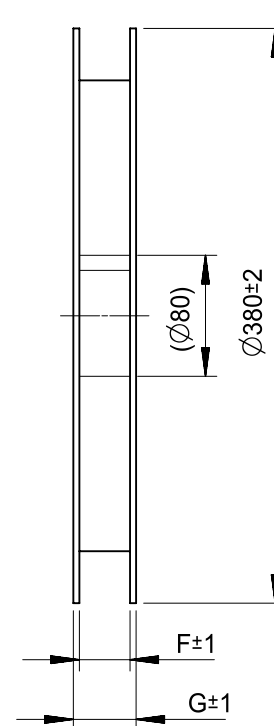
(仕上がり厚さ : 0.3±0.05)
(THICKNESS : 0.3±0.05)

FPC/FFCについて ABOUT FPC/FFC

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟箔銅35μmまたは50μmを推奨します。
FFCに規定された定格温度がFFC単体前提である場合が御座います。
コネクタと組み合わせての実使用において、接着層が劣化するなどの信頼性を満足できないケースを回避するため、実機での評価/確認をお願い致します。

RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE
RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER
NOTE: WHEN ACTUALLY USING IT WITH CONNECTOR, PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH AN ACTUAL EQUIPMENT TO EVADE THE CASE WHERE RELIABILITY CANNOT BE FILLED (THE ADHESIVE LINE OF FFC IS DETERIORATED ETC.)

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION															
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION UNITS		SCALE		CURRENT REV DESC: REVISED									
		mm		10:1											
0.25 UNDER		±0.03		GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± 1.0 ° 4 PLACES ± 0.2 3 PLACES ± 0.25 2 PLACES ± 0.3 1 PLACE ± 0.05 0 PLACES ± DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		EC NO: 637653 DRWN: TNAKAGAWA01 2020/05/15 CHK'D: HSHIMOYAMA 2020/05/15 APPR: SHOSHIKAWA 2020/05/15 INITIAL REVISION: DRWN: TRSUZUKI 2006/08/31 APPR: HHIRATA 2006/09/05 THIRD ANGLE PROJECTION DRAWING SERIES MATERIAL NUMBER CUSTOMER SHEET NUMBER									
0.25 OVER 0.5 UNDER		±0.05													
0.5 OVER 1.0 UNDER		±0.1													
1.0 OVER 10 UNDER		±0.2													
10 OVER 30 UNDER		±0.25													
30 OVER		±0.3													
ANGULAR		±1 °													
molex 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD) PRODUCT CUSTOMER DRAWING						DOCUMENT NUMBER				DOC TYPE		DOC PART		REVISION	
						SD-501951-003				PSD		001		G	
						SEE SHEET 1				GENERAL MARKET		2 OF 2			

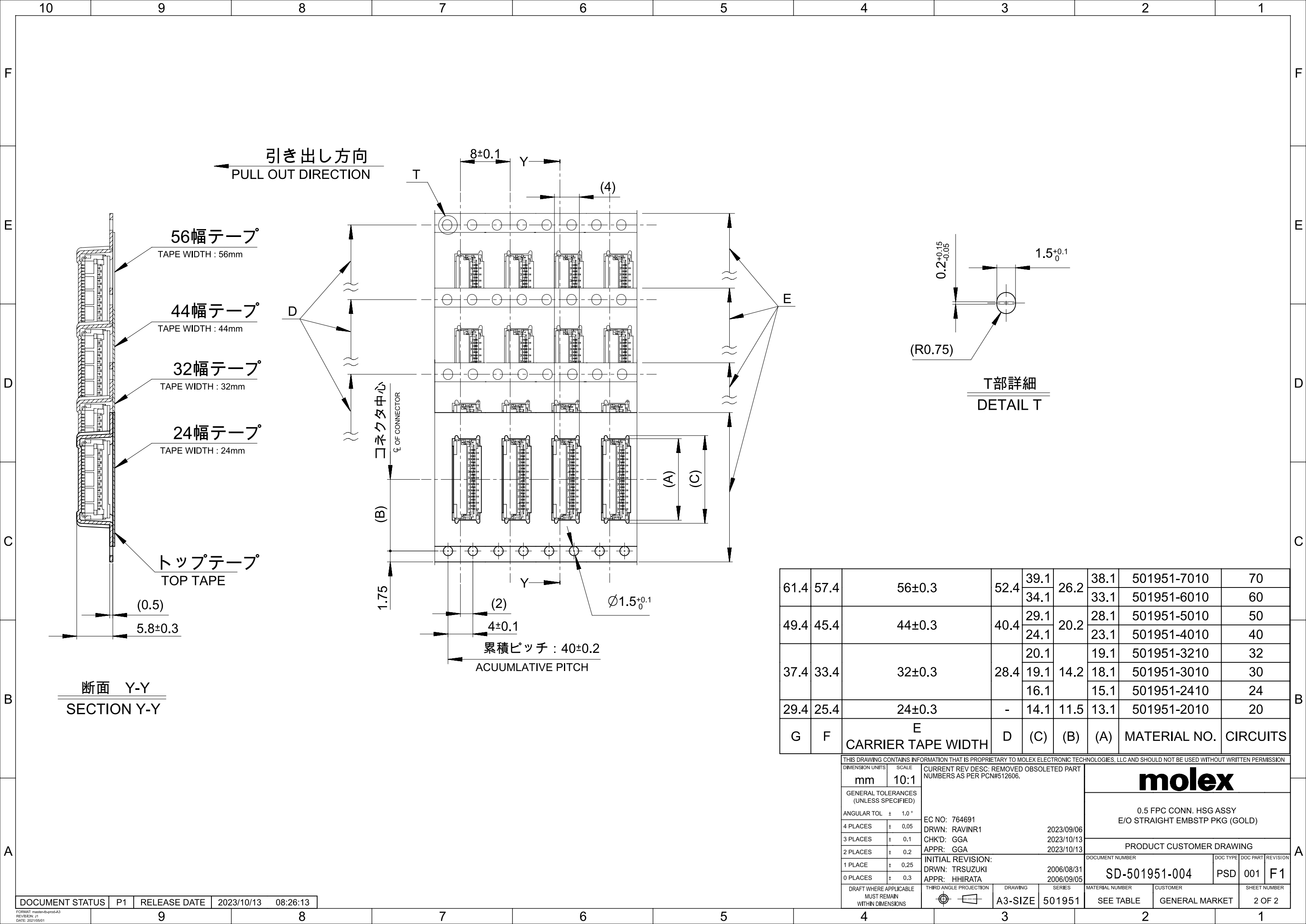


1. 製品詳細寸法については図面 SD-501951-003を参照下さい。
FOR DIMENSIONS OF PRODUCT, REFER TO SD-501951-003.
2. 梱包数量 : 2000個/リール
NUMBER OF CONNECTORS : 2000PIECES/REEL
3. リードテープ長さ
LEAD TAPE LENGTH



4. トップテープの剥離強度については、IEC60286-3に準拠
TOP TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
5. 材料 MATERIAL
キャリアテープ：ポリスチレン
CARRIER TAPE : POLYSTYRENE
トップテープ：ポリエチレンテレフタレート、ポリエチレン
TOP TAPE : POLYETHYLENE TEREPHTHALATE , POLYETHYLENE
リール：ポリスチレン<リサイクル材を含む>
REEL : POLYSTYRENE<RECYCLE MATERIAL CONTAINED>
6. ELV及びRoHS適合品 ELV AND RoHS COMPLIANT

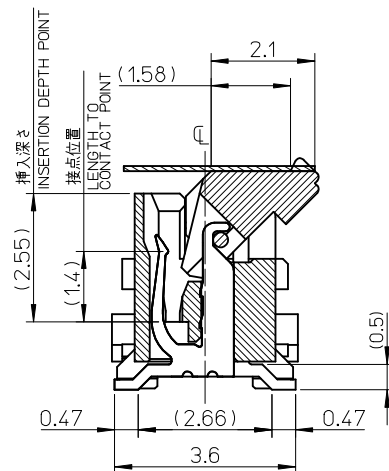
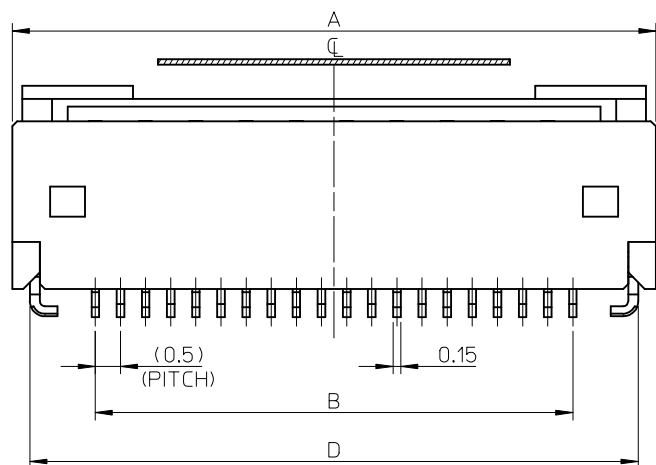
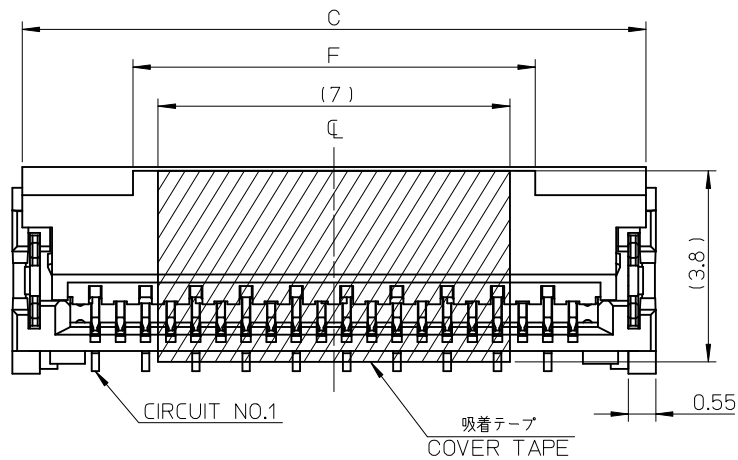
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION															
DIMENSION UNITS		SCALE		CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#512606.					molex						
mm		10:1													
GENERAL TOLERANCES (UNLESS SPECIFIED)				0.5 FPC CONN. HSG ASSY E/O STRAIGHT EMBSTP PKG (GOLD)											
ANGULAR TOL ± 1.0°															
4 PLACES		± 0.05		EC NO: 764691 DRWN: RAVINR1 2023/09/06 CHK'D: GGA 2023/10/13 APPR: GGA 2023/10/13					PRODUCT CUSTOMER DRAWING						
3 PLACES		± 0.1													
2 PLACES		± 0.2		INITIAL REVISION: DRWN: TRSUZUKI 2006/08/31 APPR: HHIRATA 2006/09/05					DOCUMENT NUMBER		DOC TYPE		DOC PART	REVISION	
1 PLACE		± 0.25							SD-501951-004		PSD		001	F1	
0 PLACES		± 0.3													
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
						A3-SIZE		501951		SEE TABLE		GENERAL MARKET		1 OF 2	



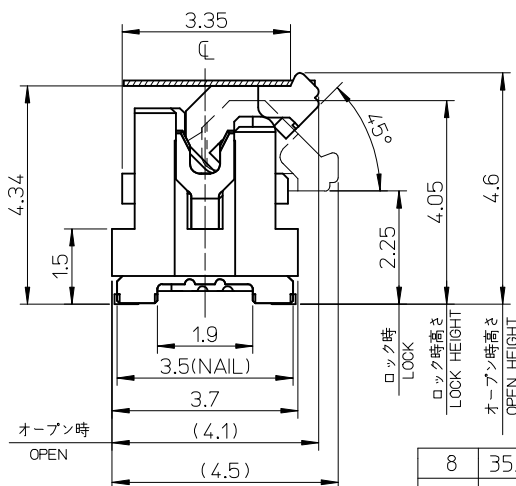
61.4	57.4	56±0.3	52.4	39.1	26.2	38.1	501951-7010	70
				34.1		33.1	501951-6010	60
49.4	45.4	44±0.3	40.4	29.1	20.2	28.1	501951-5010	50
				24.1		23.1	501951-4010	40
37.4	33.4	32±0.3	28.4	20.1	14.2	19.1	501951-3210	32
				19.1		18.1	501951-3010	30
				16.1		15.1	501951-2410	24
29.4	25.4	24±0.3	-	14.1	11.5	13.1	501951-2010	20
G	F	E CARRIER TAPE WIDTH		D	(C)	(B)	(A)	MATERIAL NO. CIRCUITS

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													
DIMENSION UNITS		SCALE		CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#512606.									
mm		10:1											
GENERAL TOLERANCES (UNLESS SPECIFIED)				EC NO: 764691 DRWN: RAVINR12023/09/06 CHK'D: GGA2023/10/13 APPR: GGA2023/10/13									
ANGULAR TOL ± 1.0 °													
4 PLACES		± 0.05											
3 PLACES		± 0.1											
2 PLACES		± 0.2											
1 PLACE		± 0.25											
0 PLACES		± 0.3											
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES					
						A3-SIZE		501951					
						DOCUMENT NUMBER				DOC TYPE	DOC PART	REVISION	
						SD-501951-004				PSD	001	F1	
						PRODUCT CUSTOMER DRAWING							
						0.5 FPC CONN. HSG ASSY E/O STRAIGHT EMBSTP PKG (GOLD)							
						MATERIAL NUMBER		CUSTOMER		SHEET NUMBER			
						SEE TABLE		GENERAL MARKET		2 OF 2			

DOCUMENT STATUS	P1	RELEASE DATE	2023/10/13	08:26:13
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断面図 (参考)
SECTION (REFERENCE)



注記 NOTES

1. 使用材料 MATERIAL

ハウジング : 液屋ポリマー ガラス充填, UL94V-0(白)
HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0 (WHITE)
アクチュエータ : ポリアミド, ガラス充填, UL94V-0(茶)
ACTUATOR POLYAMIDE, GLASS FILLED, UL94V-0 (BROWN)
ターミナル : 銅合金(t=0.15)
TERMINAL COPPER ALLOY
金具 : 銅合金(t=0.2)
FITTING NAIL COPPER ALLOY
吸着テープ : ポリアミド(t=0.125)
COVER TAPE POLYIMIDE(t=0.125)

2. めっき仕様 PLATING

ターミナル TERMINAL

コンタクト部: 部分金めっき 0.1マイクロメートル以上
CONTACT AREA :SEPARATED GOLD PLATING 0.1μm MIN.
テール部: 部分金めっき
TAIL AREA :SEPARATED GOLD PLATING
下地: ニッケルめっき 1マイクロメートル以上
UNDERPLATE: NICKEL OVERALL 1.0μm MIN.

金具 FITTING NAIL

銅めっき 1.0マイクロメートル以上
TIN PLATING 1.0μm MIN.
下地: ニッケルめっき 1マイクロメートル以上
UNDERPLATE: NICKEL OVERALL 1.0μm MIN.

3. テールと金具を併せた平坦度は 0.1ミリメートル以下
TAILS AND NAILS COPLANARITY TO BE 0.1 MAX.

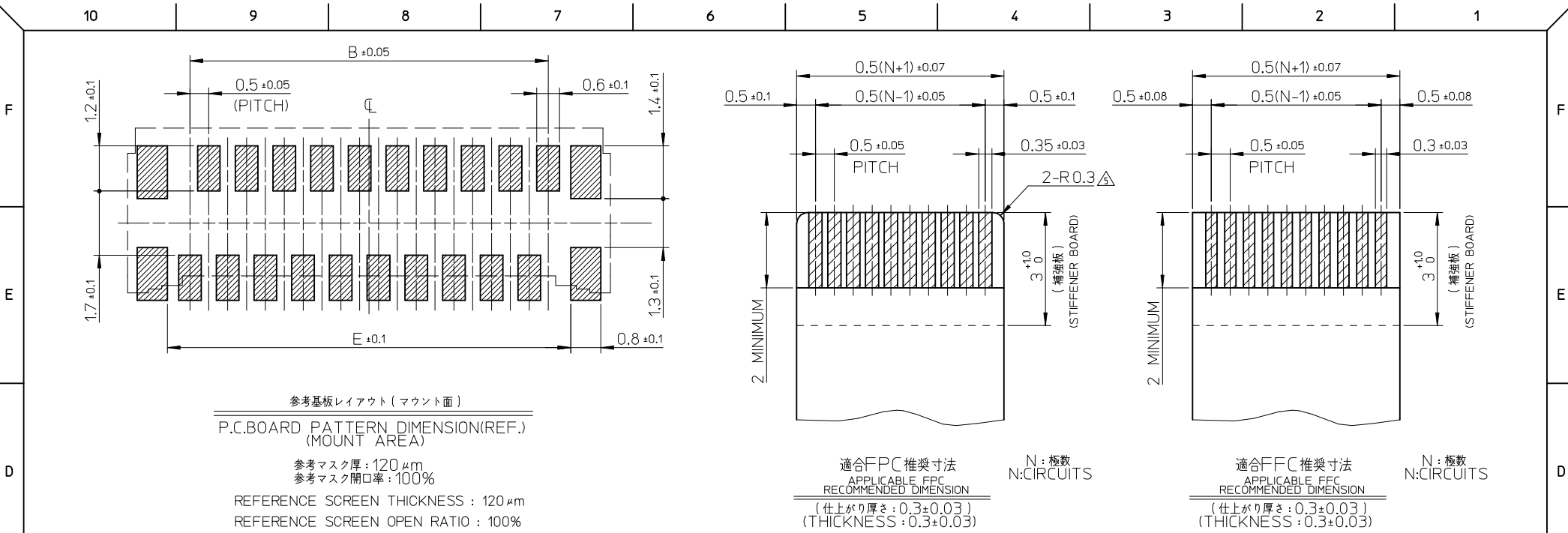
4. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

△ R0.3は、FPC導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

6. 本製品は 501951-7019 の吸着テープ付き品である。
THIS PRODUCT IS COVER TAPE VERSION OF 501951-7019.

8	35.7	37.1	37.4	34.5	37.8	501951-7020	501951-7029	70
F	E	D	C	B	A	EMBOSSED TAPE	製品番号	極数
						ORDER NO. オーダー番号	MATERIAL NO.	CIRCUITS
						MODEL NO. 501951-**-29		

RELEASED EC NO: J2016-0731 DRAWN: NKONDO CHKD: K TAKAHASHI APPR: KMORIKAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
		0.25 UNDER		± 0.2	DRAWN BY	DATE	TITLE 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD) molex		
		0.25 OVER 0.5 UNDER		± 0.2	NKONDO	2016/01/14			
		0.5 OVER 1.0 UNDER		± 0.2	CHECKED BY	DATE			
		1.0 OVER 10 UNDER		± 0.2	KTAKAHASHI	2016/01/14			
		10 OVER 30 UNDER		± 0.25	APPROVED BY	DATE	DOCUMENT NO. SD-501951-009		
		30 OVER		± 0.3	KMORIKAWA	2016/01/15			
		ANGULAR ±1 °			MATERIAL NO.			SHEET NO. 1 OF 2	
	REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25 μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。

ABOUT FPC

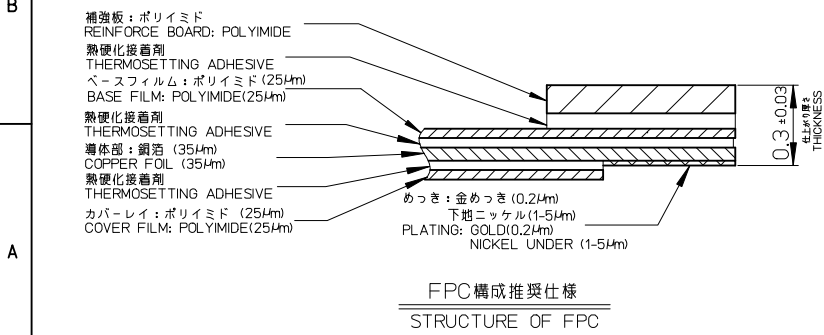
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔35 μmまたは50 μmを推奨します。
FFCに規定された定格温度がFFC単体前提である場合がございます。
コネクタと組み合わせての実使用において、接着層が劣化するなどの信頼性を満足できないケースを回避する為、実機での評価/確認をお願い致します。

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER
NOTE: WHEN ACTUALLY USING IT WITH CONNECTOR, PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH AN ACTUAL EQUIPMENT TO EVADE THE CASE WHERE RELIABILITY CANNOT BE FILLED (THE ADHESIVE LINE OF FFC IS DETERIORATED ETC.)



RELEASED EC NO: J2016-0731 O	2016/01/14 DRWN: NKONDO 2016/01/14 CHKD: TAKAHASHI 2016/01/14 APPR: KMORI KAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
			0.25 UNDER		± 0.2	DRAWN BY	DATE	TITLE 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD)		
			0.25 OVER	0.5 UNDER	± 0.2	NKONDO	2016/01/14			
			0.5 OVER	1.0 UNDER	± 0.2	CHECKED BY	DATE	--- molex		
			1.0 OVER	10 UNDER	± 0.2	TAKAHASHI	2016/01/14			
			10 OVER	30 UNDER	± 0.25	APPROVED BY	DATE			
			30 OVER		± 0.3	KMORIKAWA	2016/01/15			
REV						MATERIAL NO.	DOCUMENT NO.		SHEET NO.	
			ANGULAR ±1 °			SEE SHEET 1	SD-501951-009		2 OF 2	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			